

TOPCon主栅浆料
TOPCon Busbar Paste

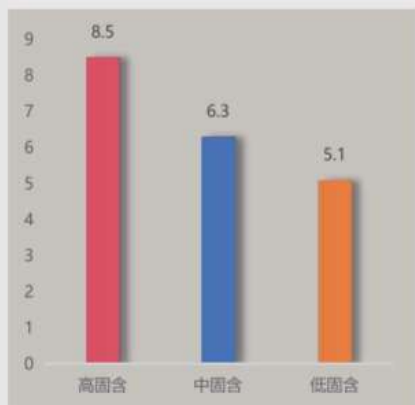
GD127/GD501系列
GD127/GD501 Series

适用范围
Application

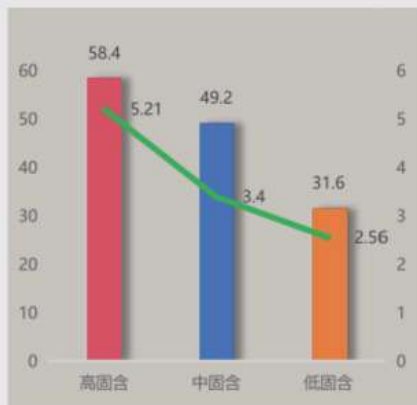
- 适用于TOPCon正、背面主栅电极，常规烧结及激光辅助烧结工艺，亦可结合客户端需求，单独设计针对性的浆料，匹配高速印刷及各种网版参数
Suitable for TOPCon front-side and rear-side busbar in both conventional firing and laser-assisted firing processes. Customizable paste formulations can be tailored based on specific customer requirements to match high-speed printing and various screen-printing parameters.

亮点
Highlights

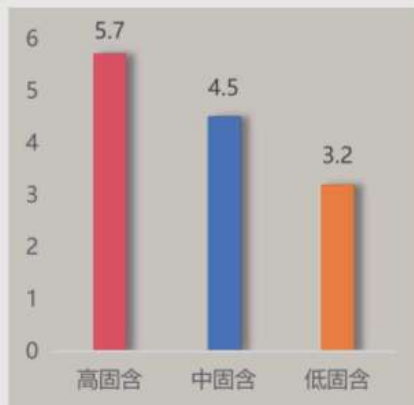
- 针对性开发无机体系，匹配细栅浆料，收获更高Uoc/FF性能
Specially developed inorganic vehicle system, formulated to match with fine grid pastes, achieving higher Uoc (Open-circuit voltage) and FF (Fill Factor) performance.
- 可根据客户不同需求提供74-87%多梯度固含，兼顾导电性能/焊接拉力/老化拉力/印刷良率等指标要求
Provides multi-gradient solid content options (74-87%) to meet diverse customer requirements, maintaining a balanced performance across critical indicators such as electrical conductivity, solder pull strength, aged pull strength, and printing yield.
- 自主银粉，配方调整空间大，可匹配较窄主栅连接线网版
Utilizing in-house silver powder with extensive formulation adjustment flexibility, well-suited for screen printing with narrow busbar connecting lines.



主栅湿重 (mg)
Busbar Wet Weight (mg)



主栅连接线——高宽对比
Busbar Connecting Lines - Height Comparison



主栅PAD点高度
Busbar Pad Height

类型 (Type)	Eta (%)	Uoc (V)	Isc (A)	FF (%)
BSL	/	/	/	/
GD127系列 GD127 Series	0.019	0.0002	—	0.05